

Parameter	Rating	Units
Blocking Voltage	60	V <sub>P</sub>
Load Current	3.25	A <sub>DC</sub>
On-Resistance (max)	0.09	Ω

#### **Features**

- 3.25A<sub>DC</sub> Load Current
- 60V Blocking Voltage
- 90mΩ Maximum On-Resistance
- 5mA Input Control Current to Activate
- 2500V<sub>rms</sub> Input/Output Isolation
- Power SIP Package
- · Greater Reliability than Electromechanical Relays
- No EMI/RFI Generation
- Flammability Rating UL 94 V-0

## **Applications**

- Transportation Railroad Controls
- Security
- Battery Backup Systems
- Industrial Controls
- Robotics
- Instrumentation

#### **Description**

The CPC1705Y is a 60V,  $3.25A_{DC}$ ,  $0.09\Omega$  DC-switching, normally closed (1-Form-B) Solid State Relay. To minimize printed circuit board space, this device is provided in IXYS Integrated Circuits' Power Single In-line package (PowerSIP).

Employing optically coupled MOSFET technology, the CPC1705Y provides 2500V<sub>rms</sub> of input to output isolation. The relay output is constructed with an efficient MOSFET switch that utilizes IXYS Integrated Circuits' patented OptoMOS architecture. A highly efficient infrared LED at the input controls the optically coupled output.

The combination of low on-resistance and high load current capability makes this relay suitable for a variety of high performance switching applications.

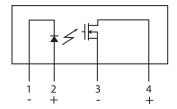
#### **Approvals**

UL 508 Certified Component: File E69938

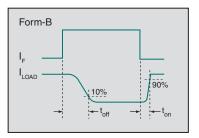
## **Ordering Information**

Part #	Description
CPC1705Y	4-Pin (8-Pin Body) Power SIP Package (25 per tube)

## **Pin Configuration**



#### Switching Characteristics of Normally Closed Devices











# Absolute Maximum Ratings @ T<sub>A</sub>=25°C (Unless Otherwise Noted)

Parameter	Ratings	Units
Blocking Voltage	60	$V_P$
Reverse Input Voltage	5	V
Input control Current	50	mA
Peak (10ms)	1	Α
Input Power Dissipation <sup>1</sup>	150	mW
Total Power Dissipation <sup>2</sup>	1175	mW
Isolation Voltage, Input to Output	2500	$V_{rms}$
ESD Rating (Human Body Model)	4	kV
Operational Temperature, Ambient	-40 to +85	°C
Storage Temperature	-40 to +125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

# Electrical Characteristics @ T<sub>A</sub>=25°C (Unless Otherwise Noted)

	A \ \							
Parameter	Conditions	Symbol	Min	Тур	Max	Units		
Output Characteristics	·							
Blocking Voltage	I <sub>L</sub> =1μA	$V_{DRM}$	60	-	-	V		
Load Current								
Continuous 1	Free Air	$I_{L}$	-	-	3.25	A <sub>DC</sub>		
Peak	t=10ms	I <sub>LPK</sub>	-	-	3.25	A		
On-Resistance <sup>2</sup>	I <sub>L</sub> =1A	R <sub>ON</sub>	-	0.059	0.09	Ω		
Off-State Leakage Current	$I_F=5mA, V_L=60V_{DC}$	I <sub>LEAK</sub>	-	-	1	μΑ		
Switching Speeds								
Turn-On	L =10mA \/ =10\/	t <sub>on</sub>	-	0.6	2	ms		
Turn-Off	I <sub>F</sub> =10mA, V <sub>L</sub> =10V	t <sub>off</sub>	-	2.84	12	1115		
Output Capacitance	$I_F=10\text{mA}, V_L=20V_{DC}, f=1\text{MHz}$	C <sub>OUT</sub>	-	1	-	nF		
Input Characteristics								
Input Control Current to Activate 3	I <sub>L</sub> =0A	I <sub>F</sub>	-	0.8	5	mA		
Input Control Current to Deactivate	ol Current to Deactivate I <sub>L</sub> =1A		0.1	0.8	-	mA		
Input Voltage Drop	I <sub>F</sub> =5mA	V <sub>F</sub>	0.9	1.36	1.5	V		
everse Input Current V <sub>R</sub> =5V		I <sub>R</sub>	-	-	10	μΑ		
Input/Output Characteristics						•		
Capacitance, Input-to-Output	V <sub>IO</sub> =0V, f=1MHz	C <sub>IO</sub>	-	2	-	pF		
					_			

#### **Thermal Characteristics**

Parameter	Symbol	Rating	Units
Thermal Impedance (Junction to Ambient)	$\theta_{JA}$	85	°C/W

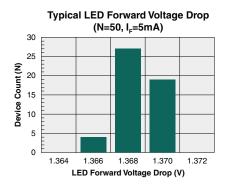
<sup>1</sup> Derate linearly 1.33 mW / °C

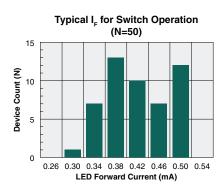
<sup>&</sup>lt;sup>2</sup> Derate Output Power linearly 11.8 mW / °C

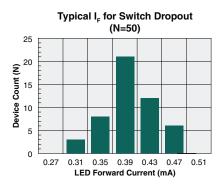
Derate linearly 20.5 mA/°C. Measurement taken within 1 second of on-time. For high-temperature operation ( $T_A$  > 60°C) a minimum LED drive current of 10mA is recommended.

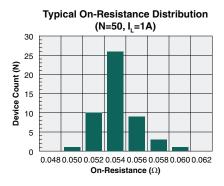


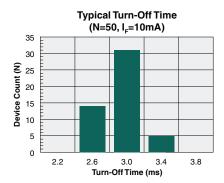
#### **PERFORMANCE DATA\***

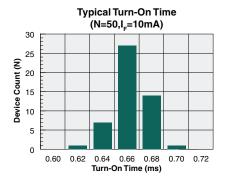


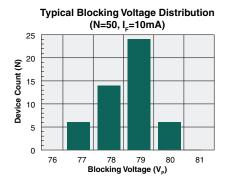


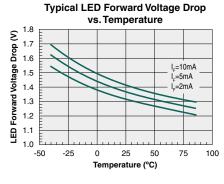


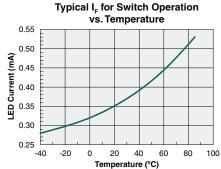


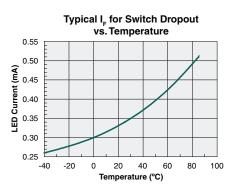












\*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.

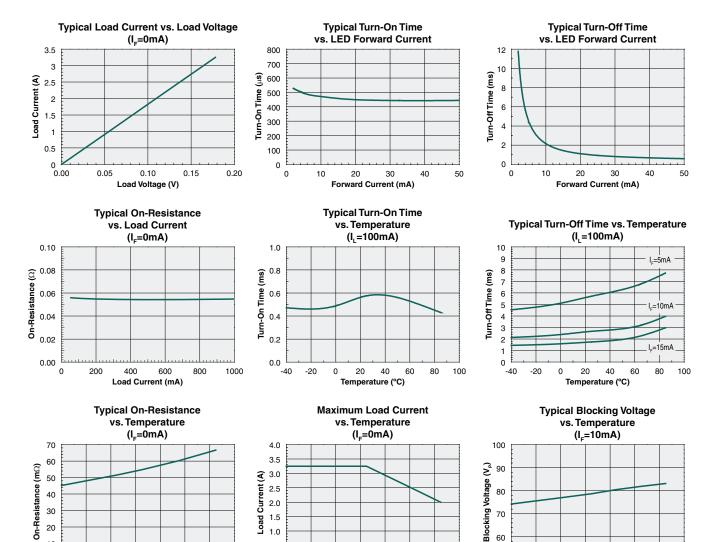


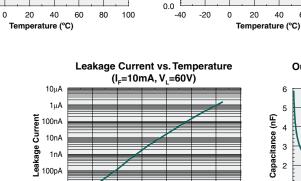
20

10

-40 -20

#### **PERFORMANCE DATA\***



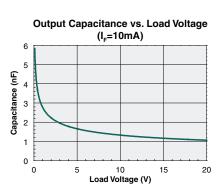


Temperature (°C)

10pA 1pA -40 -20 0 20 40 60 80 100

1.0

0.5



70

60

-40 -20 0 40 60 80 100

Temperature (°C)

20

20 40 60 80 100

<sup>\*</sup>Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.



#### **Manufacturing Information**

#### **ESD Sensitivity**



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

#### **Soldering Profile**

For through-hole devices, the maximum pin temperature and maximum dwell time through all solder waves is provided in the table below. Dwell time is the interval beginning when the pins are initially immersed into the solder wave until they exit the solder wave. For multiple waves, the dwell time is from entering the first wave until exiting the last wave. During this time, pin temperatures must not exceed the maximum temperature given in the table below. Body temperature of the device must not exceed the limit shown in the table below at any time during the soldering process.

Device	Maximum Pin Temperature	Maximum Body Temperature	Maximum Dwell Time	Wave Cycles
CPC1705Y	260°C	245°C	10 seconds*	1

<sup>\*</sup>Total cumulative duration of all waves.

#### **Board Wash**

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.





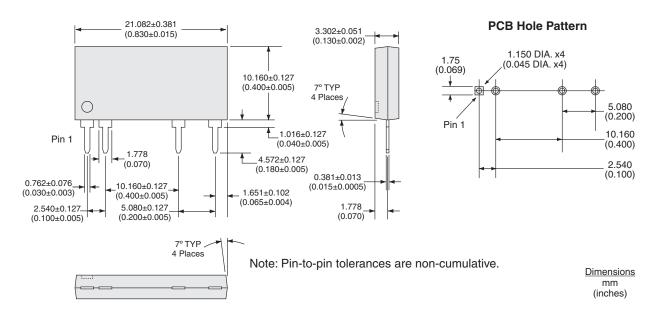


R04 www.ixysic.com 5



#### **MECHANICAL DIMENSIONS**

# **CPC1705Y Package**



For additional information please visit our website at: https://www.ixysic.com



Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at https://www.littelfuse.com/disclaimer-electronics.

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Solid State Relays - PCB Mount category:

Click to view products by IXYS manufacturer:

Other Similar products are found below:

M86F-2W M90F-2Y G2-1A07-ST G2-1A07-TT G2-1B02-TT G2-DA06-ST 923812OCAS PLA134S DS11-1005 AQH3213J AQV212J AQY412EHAJ EFR1200480A150 901-7 LCA220 LCB110S 1618400-5 SR75-1ST AQH2213AJ AQV112KLJ AQV212AJ AQV212SXJ AQV238AD01 AQW414TS AQY221N2SYD01 AQY221R2VJ AQY275AXJ AQY414SXE01 G2-1A02-ST G2-1A03-ST G2-1A03-TT G2-1A05-ST G2-1A06-TT G2-1B01-ST G2-1B01-TT G2-1B02-ST G2-DA03-ST G2-DA03-TT G2-DA06-TT CPC1333GR 3-1617776-2 CTA2425 TLP3131(F) LBA110S LBB110S LCA110LSTR LCB126S WPPM-0626D WPPM-3526D